

E  
 y)  
 PATENT & TRADEMARK OFFICE  
 JUN 14 2002  
 JC103

Application Number	09/386,734
Confirmation Number	1735
Filing Date	08/31/99
First Named Inventor	Thomas Ritzdorf
Group Art Unit	1742
Examiner Name	G Wyszomierski
Attorney Docket No.	291958170US

Sheet	1	of
-------	---	----

[illegible]

RECEIVED  
JUN 25 2002  
TECHNOLOGY CENTER 1700

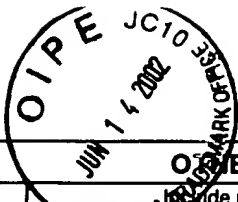
[illegible]

Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume issue number(s), publisher, city and/or country where published.	T
Ca		AHN, E.C., et al "Adhesion Reliability of Cu-Cr Alloy Films To Polyimide," Met. Res. Soc. Symp. Proc. Vol. 427, 1996 Materials Research Society, pp. 141-145	
Ca		ALERS, G.B., "Trade-off between reliability and post-CMP defects during recrystallization anneal for copper damascene interconnects," IEEE International Reliability Physics Symposium, Orlando, Florida 2001, pp. 350-354	

G. A. Jones

9/4/02

Form 1449.doc



OTHER PRIOR ART-NON PATENT LITERATURE DOCUMENTS

Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume issue number(s), publisher, city and/or country where published.	T
Gu		GLADKIKH, A. et al, "Activation Energy of Electromigration in Copper Thin Film Conductor Lines," Met. Res. Soc. Symp. Proc. 1996 Materials Research Society, pp. 121-133	
Gu		KONONENKO, O.V. et al. "Electromigration in Submicron Wide Copper Lines," Met. Res. Soc. Symp. Proc. 1996 Materials Research Society, pp. 127-133	
Gu		MEL, YU-JANE et al. "Thermal Stability and Interaction Between SiO <sub>2</sub> and Cu Film," Met. Res. Soc. Symp. Proc. Vol 427, 1996 Materials Research Society, pp. 433-439	
Gu		RUSSELL, S.W. et al. The Effect of Copper on the Titanium-Silicon Dioxide Reaction and the Implications for Self-Encapsulating, Self-Adhering Metallization Lines," Materials Research Society Symposium Vol 260 (May 1992) pp 763-767	
		Gu, Ulyut 9/4/02	

RECEIVED  
JUN 25 2002  
TECHNOLOGY CENTER 1700